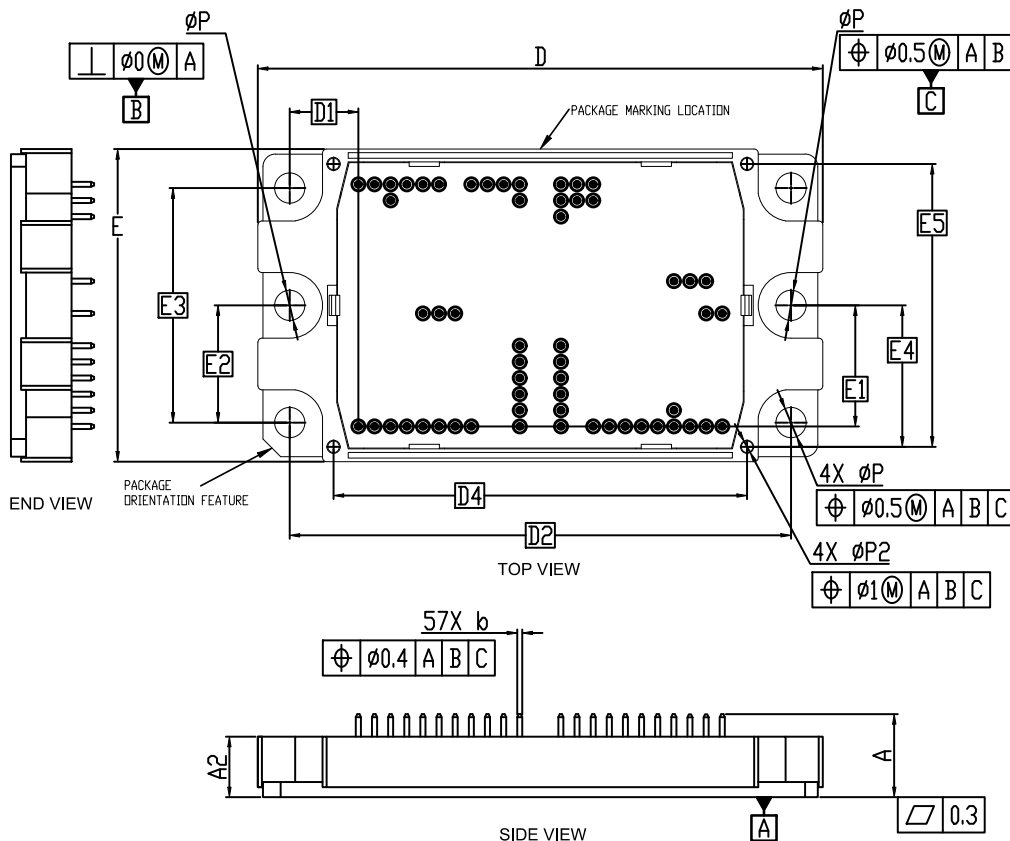


PIM57 112.00x62.00x12.00
CASE 180CV
ISSUE O

DATE 30 JUL 2024

NOTES:

1. Dimensioning and tolerancing conform to ASME Y14.5
2. All dimensions are in millimeters.
3. Pin-grid is 3.2mm.
4. Package marking is located on the side opposite the package orientation feature.
5. The pins are gold-plated solder pin.



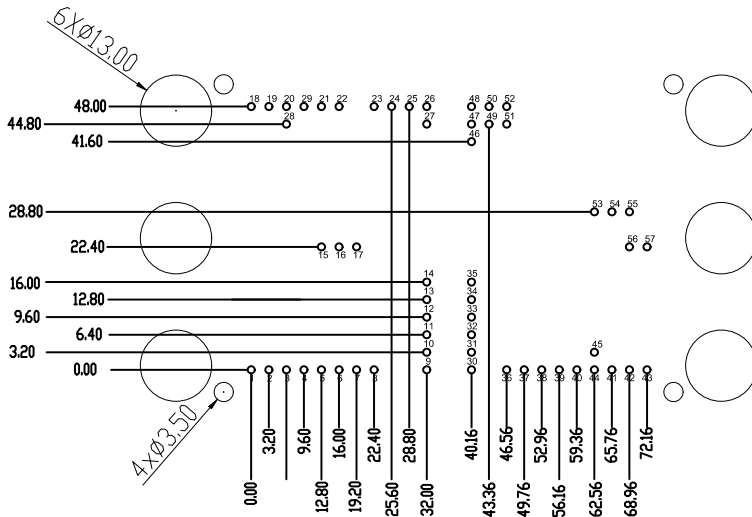
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	16.10	16.50	16.90
A2	11.70	12.00	12.30
b	0.95	1.00	1.05
D	111.60	112.00	112.40
D1		13.62 BSC	
D2		99.40 BSC	
D4		82.00 BSC	
E	61.60	62.00	62.40
E1		24.00 BSC	
E2		23.25 BSC	
E3		46.50 BSC	
E4		28.05 BSC	
E5		56.10 BSC	
P	5.90	6.00	6.10
P2	2.20	2.30	2.40

DOCUMENT NUMBER:	98AON63823H	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	PIM57 112.00x62.00x12.00	PAGE 1 OF 2

onsemi and onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

PIM57 112.00x62.00x12.00
CASE 180CV
ISSUE O

DATE 30 JUL 2024



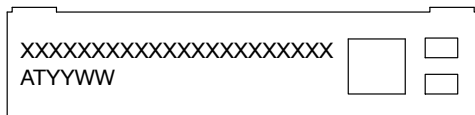
RECOMMENDED
MOUNTING PATTERN

* For additional information on our Pb-Free strategy and soldering details, please download the Onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

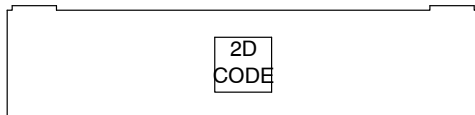
NOTE 2:

Pin table								
Pin	X	Y	Pin	X	Y	Pin	X	Y
1	0	0	23	22.4	48	45	62.56	3.2
2	3.2	0	24	25.6	48	46	40.16	41.6
3	6.4	0	25	28.8	48	47	40.16	44.8
4	9.6	0	26	32	48	48	40.16	48
5	12.8	0	27	32	44.8	49	43.36	44.8
6	16	0	28	6.4	44.8	50	43.36	48
7	19.2	0	29	9.6	48	51	46.56	44.8
8	22.4	0	30	40.16	0	52	46.56	48
9	32	0	31	40.16	3.2	53	62.56	28.8
10	32	3.2	32	40.16	6.4	54	65.76	28.8
11	32	6.4	33	40.16	9.6	55	68.96	28.8
12	32	9.6	34	40.16	12.8	56	68.96	22.4
13	32	12.8	35	40.16	16	57	72.16	22.4
14	32	16	36	46.56	0			
15	12.8	22.4	37	49.76	0			
16	16	22.4	38	52.96	0			
17	19.2	22.4	39	56.16	0			
18	0	48	40	59.36	0			
19	3.2	48	41	65.76	0			
20	6.4	48	42	68.96	0			
21	12.8	48	43	72.16	0			
22	16	48	44	62.56	0			

GENERIC
MARKING DIAGRAM*



FRONTSIDE MARKING



BACKSIDE MARKING

XXXXXX = Specific Device Code
AT = Assembly & Test Site Code
YYWW = Year and Work Week Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	98AON63823H	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	PIM57 112.00x62.00x12.00	PAGE 2 OF 2

onsemi and onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.